



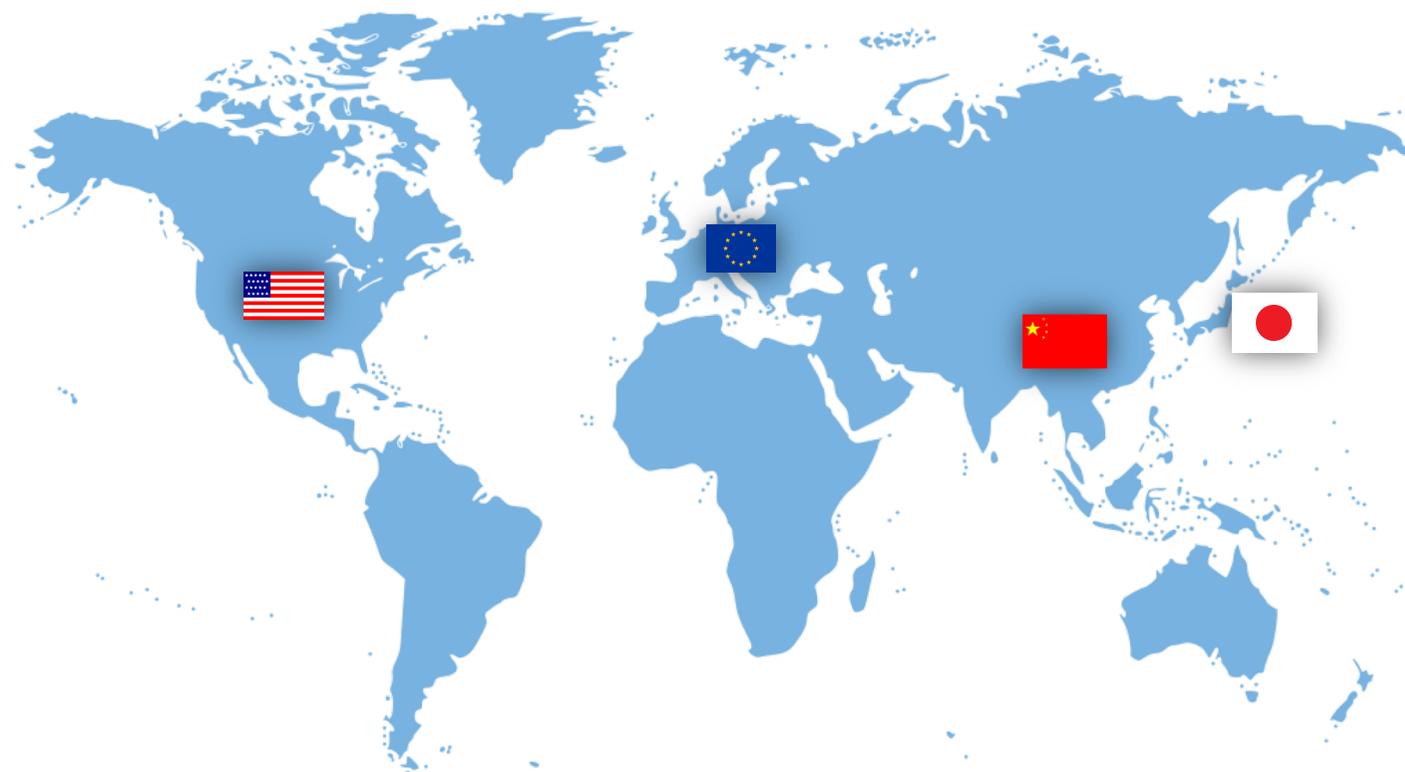
Au service de la recherche scientifique, l'innovation et la compétitivité des entreprises *À la croisée des révolutions numériques*

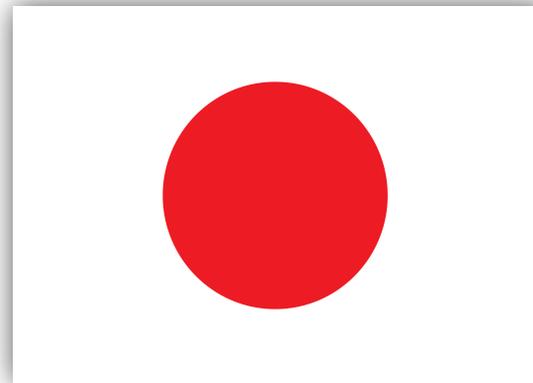
Vision des architectures pour l'Exascale, panorama international

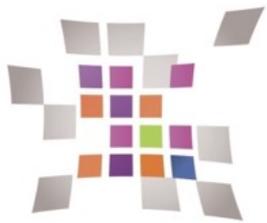
S. Réquena – GENCI
C. Calvin – ARISTOTE
F. Boillod-Cerneux - CEA



AGENDA





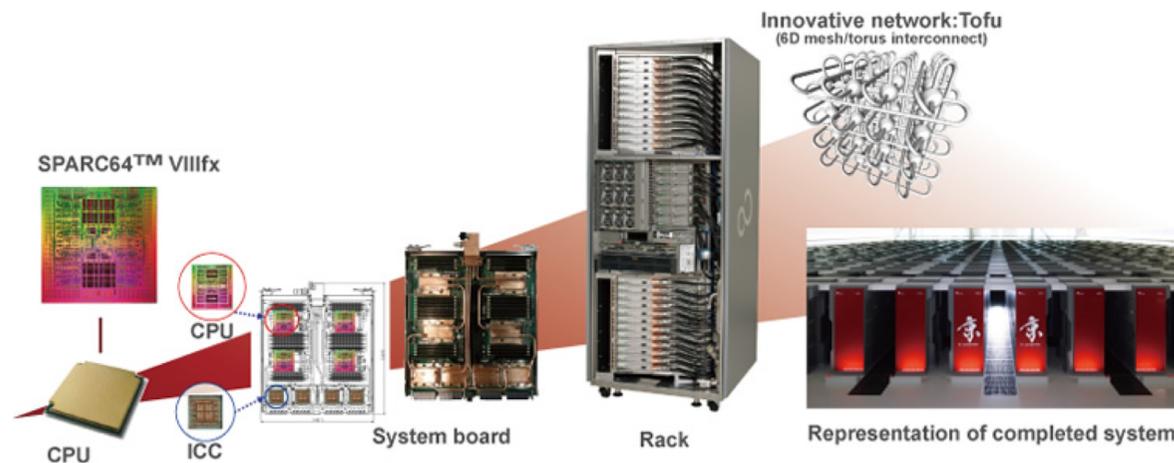


L'EXASCALE AU JAPON

Post-K au RIKEN

□ Successeur du K-Computer (2011-2019) 京, *kei*, qui signifie 10^{16}

- Système Fujitsu de 11.3 PFlop/s crête installé au Riken (Kobe) en 2011
- Architecture MPP
 - 864 racks avec chacun 24 cartes de 4 nœuds mono socket Sparc VIIIfx 8-core 2.0 GHz (45nm, 128 GF), 16 GB de mémoire
 - 88 128 processeurs **soit 705 024 cœurs et 1.26 PB de mémoire dist.** au total
 - Interconnect propriétaire **Tofu 6D torique** avec liens 5GB/s bi directionnels
 - Refroidissement liquide - consommation totale = **12.6MW**
 - Stack logicielle optimisée : micro kernel, OpenMPI, MPI, auto // Fortran 90, Lustre, ...
 - Nœud de calcul très équilibré : **0.5 bytes/flops** (bw mémoire, réseau, ...)
- #1 du top500 de juin 2011 à juin 2012 (now #18), #1 graph500 (BFS) depuis 2014 et #1 ou #2 du HPCG depuis 2016





L'EXASCALE AU JAPON

Post-K au RIKEN



□ Comme pour tout Tier0 japonais → Méthodologie de co design

- 2012-2013 : études de faisabilité : 3 équipes architecture en compétition (NEC, Hitachi et **Fujitsu**) et 1 équipe applications
 - 9 applications retenues : médical/pharma, environnement/prévention risques, énergie, manufacturing, ...
 - Utilisation de simulateurs/estimateurs performances sur kernels, mini et full apps
 - Impact vectorisation, #core, #NUMA node, interconnect, HBM, ...
- Avril 2014 : démarrage projet Post K avec budget proche de 1Md\$ et **objectif 100x soutenus / K computer sur applications concrètes**
- Aout 2017 : Hotchips conférence -> annonce support processeur ARM
- Aout 2018 : annonces processeur ARM64fx et réseau Tofu2 par Fujitsu
- 1H 2019 : démarrage fabrication Post-K
- Aout 2019 : fin des activités du K-Computer
- 4Q2019-1Q2020 : installation Post-K
- 1H2020 : pré production Post-K
- 2020-2021 : pleine production Post-K

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L'EXASCALE AU JAPON



Post-K au RIKEN

□ Post K une architecture MPP manycore **convergée** (HPC+IA)

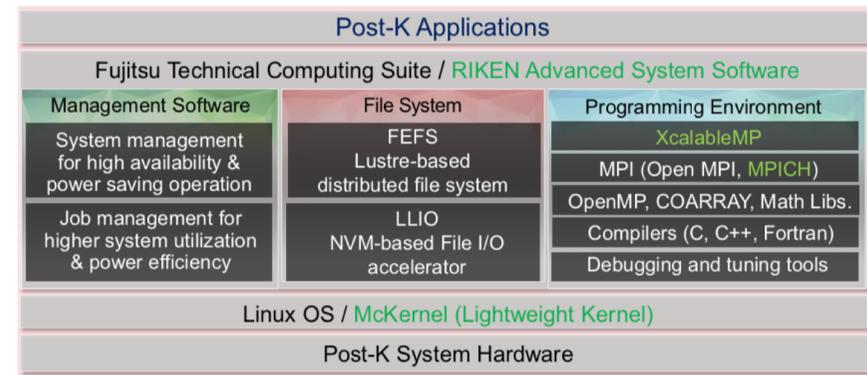
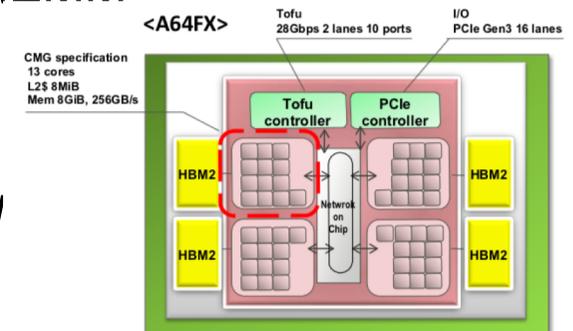
- Nœud mono ARM v8-A A64FX (**48 compute+4 OS core**), SVE 512, 7nm
- 4 core memory group (4 espaces NUMA) de 12 + 1 cœurs
- **>2.7 TF peak** (FP64), >5.4 TF (FP32), >10.8 (INT16 DP) et > 21.6 (INT8 DP)
- **32 GB HBM3** (1 Go/s débit, >80% @Stream TRIAD) → 0.66 GB/core
- Bon équilibre nœud avec **0.4 Bytes/Flop** et >90% @DGEMM

□ Fédérée par un interconnect **TOFU-D** next gen

- Topologie 6D Torique (comme K computer)
- *0,49 us de latence et 38.1 Go/s débit soutenu per nœud*

□ Specs machine complète

- *>150 000 nodes, 8 millions de cœurs de calcul -> environ 0.5 EF peak*
- 3 niveaux stockage (burst buffers, Lustre, Cloud)
- 400 racks, refroidissement DLC
- 40MW consommation totale
- Stack logicielle optimisée



Post K sera un produit commercial de Fujitsu



L'EXASCALE AU JAPON

Post-K au RIKEN

FLAGSHIP 2020 Project



The project is backed by Japan's Ministry of Education, Culture, Sports, Science and Technology.

Health and longevity		Disaster prevention / Environment		Energy issues		Industrial competitiveness enhancement		Basic science	
01	Innovative drug discovery infrastructure through functional control of biomolecular systems	03	Development of integrated simulation systems for hazards and disasters induced by earthquakes and tsunamis	05	Development of new fundamental technologies for highly-efficient energy creation, conversion, storage and use	07	Creation of new functional devices and high-performance materials to support next-generation industries	09	Elucidation of the fundamental laws and evolution of the universe
02	Integrated computational life science to support personalized and preventive medicine	04	Advancement of meteorological and global environmental predictions utilizing observational "Big Data"	06	Accelerated development of innovative clean energy systems	08	Development of innovative design and production processes that lead the way for the manufacturing industry in the near future		
Details	Details	Details	Details	Details	Details	Details	Details	Details	

Exploratory Challenge

- 01** Frontiers of Basic Science: Challenging the Limits
- 02** Construction of Models for Interaction Among Multiple Socioeconomic Phenomena
- 03** Elucidation of the Birth of Exoplanets [Second Earth] and the Environmental Variations of Planets in the Solar System
- 04** Elucidation of How Neural Networks Realize Thinking and Its Application to Artificial Intelligence

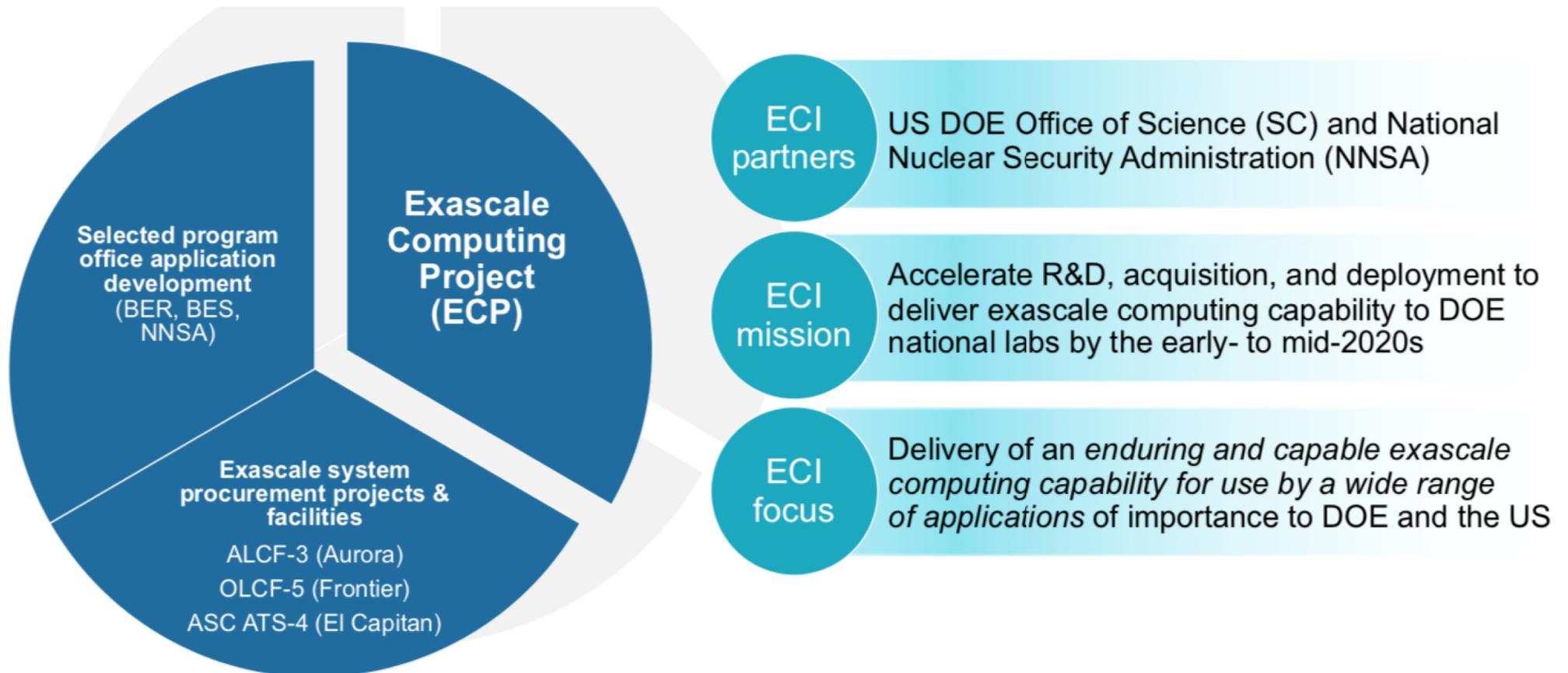




L'EXASCALE AUX ETATS-UNIS

ECI : Exascale Computing Initiative

- Juillet 2015 : signature de l'executive order Exascale par B. Obama et mise en place de la National Strategic Computing Initiative (NSCI)
- 2017 : Exascale Computing Initiative pour DoE et NNSA





L'EXASCALE AUX ETATS-UNIS

Ne pas oublier aussi !

Décret de D. Trump sur l'IA US



- ❑ Executive Order en date du 11 février
- ❑ U.S Artificial Intelligence Initiative « *Maintaining/Accelerating American Leadership in Artificial Intelligence* »
- ❑ 6 objectifs dont notamment
 - Investissements publics dans R&D en IA
 - Priorisation des investissements agences publiques dans IA
 - Mise à disposition de ressources HPC pour IA
 - Agences fédérales devront ouvrir leurs moyens HPC à R&D IA
 - Gouvernance pour guider développement IA
 - Fiabilité, sécurité et interopérabilité (standards)
 - Formation
 - Tous cycles & filières apprentissage pour aide au changement travailleurs impactés
- ❑ Pas de budget annoncé

<https://www.whitehouse.gov/articles/accelerating-americas-leadership-in-artificial-intelligence/>



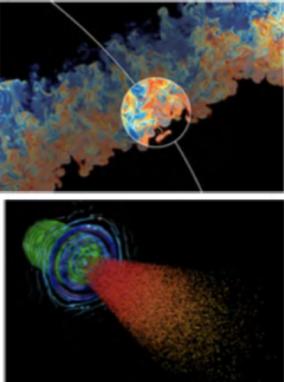
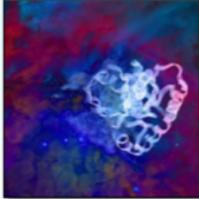
L'EXASCALE AUX ETATS-UNIS

ECP : Exascale Computing Project



□ Co design et développement de nouvelles approches (HPC+IA)

- 25 applications sélectionnées
- > 80 outils et environnements : MPI, OpenMP, OpenACC, LLVM, PAPI/TAU, BLAS, ADIOS, HDF5, Paraview ... mais aussi Raja, Kokkos, spack, UnifyCR, ...
- Extreme Scale Scientific Software Stack (e4s.io)
- Forte contribution dans standards

National security	Energy security	Economic security	Scientific discovery	Earth system	Health care
<p>Next-generation, stockpile stewardship codes</p> <p>Reentry-vehicle-environment simulation</p> <p>Multi-physics science simulations of high-energy density physics conditions</p>	<p>Turbine wind plant efficiency</p> <p>Design and commercialization of SMRs</p> <p>Nuclear fission and fusion reactor materials design</p> <p>Subsurface use for carbon capture, petroleum extraction, waste disposal</p> <p>High-efficiency, low-emission combustion engine and gas turbine design</p> <p>Scale up of clean fossil fuel combustion</p> <p>Biofuel catalyst design</p>	<p>Additive manufacturing of qualifiable metal parts</p> <p>Urban planning</p> <p>Reliable and efficient planning of the power grid</p> <p>Seismic hazard risk assessment</p>	<p>Cosmological probe of the standard model of particle physics</p> <p>Validate fundamental laws of nature</p> <p>Plasma wakefield accelerator design</p> <p>Light source-enabled analysis of protein and molecular structure and design</p> <p>Find, predict, and control materials and properties</p> <p>Predict and control stable ITER operational performance</p> <p>Demystify origin of chemical elements</p>	<p>Accurate regional impact assessments in Earth system models</p> <p>Stress-resistant crop analysis and catalytic conversion of biomass-derived alcohols</p> <p>Metagenomics for analysis of biogeochemical cycles, climate change, environmental remediation</p>	<p>Accelerate and translate cancer research (partnership with NIH)</p>
					



L'EXASCALE AUX ETATS-UNIS

ECP : Exascale Computing Project



ECP by the Numbers

7 YEARS
\$1.7B

A seven-year, \$1.7 B R&D effort that launched in 2016

6 CORE DOE LABS

Six core DOE National Laboratories: Argonne, Lawrence Berkeley, Lawrence Livermore, Oak Ridge, Sandia, Los Alamos

- Staff from most of the 17 DOE national laboratories take part in the project

3 FOCUS AREAS

Three technical focus areas: Hardware and Integration, Software Technology, Application Development supported by a Project Management Office

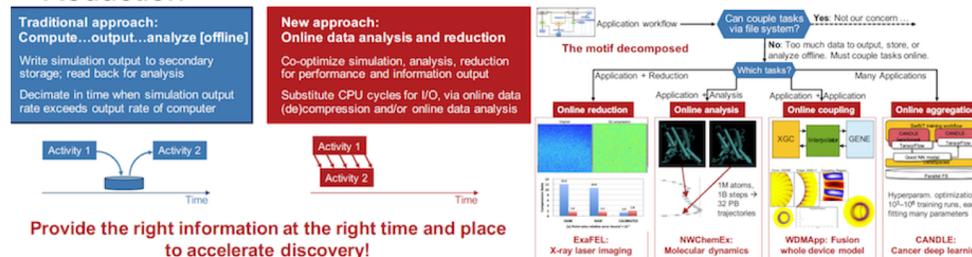
100 R&D TEAMS
1000 RESEARCHERS

More than 100 top-notch R&D teams

Hundreds of consequential milestones delivered on schedule and within budget since project inception



ECP's Co-Design Center for Online Data Analysis and Reduction



Provide the right information at the right time and place to accelerate discovery!

Goal: Replace the activities in HPC workflow that have been mediated through file I/O with in-situ methods / workflows. data reduction, analysis, code coupling, aggregation (e.g. parameter studies).

Cross-cutting tools:

- Workflow setup, manager (Cheetah, Savanna); Data coupler (ADIOS-SST); Compression methods (MGARD, FTK, SZ), compression checker (Z-checker)
- Performance tools (TAU, Chimbuco, SOSFlow)

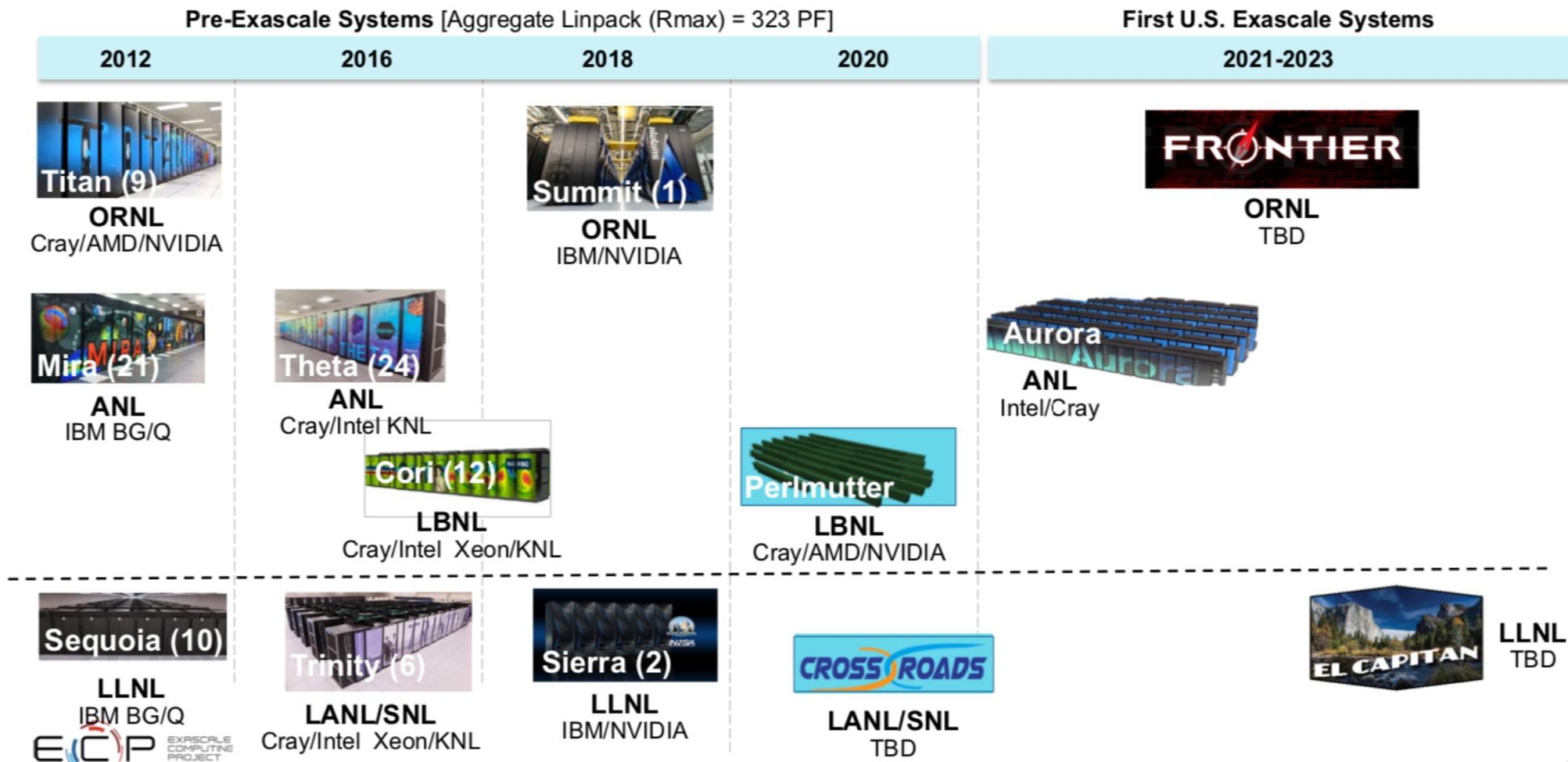


PI: Ian Foster (ANL)



L'EXASCALE AUX ETATS-UNIS

Roadmap DoE sur 1 slide





L'EXASCALE AUX ETATS-UNIS

Ou deux avec en plus NSF (TACC)

	A21	A22	Frontier (OLCF5)	El Capitan (ATS-4)	NERSC-10	NSF Frontera Follow-on
Location	ANL	ANL	ORNL	LLNL	LBNL/NER SC	TACC
Planned Delivery Date/ Estimated	2022 Q1	2022	2022 Q1	2022	2024	2024
Early Operation	2022, Q2	2023	2022, Q3	2023	2025	2025
Planned/Realized Performance (Pflops)	~1,000	1,300 or higher	1500-3000	4000-5000	8000-12000	500
Linpack Performance (PFlops)	800-900	780-1040	900-2100	2000-3000	2000-3000	
Linpack/Peak Performance Ratio (%)	80-90 (est.)	60-70 (est.)	60-70 (est.)	50-60	50-60	50-55
High Performance Conjugate Gradient (PFlops/s)	20.0-22.5	19.5-26.0	18-36	48-72	52-78	74
GF/Watt	40		60-100	134-200	266-480	

Source : Hyperion HPC User Forum, mars 2019



L'EXASCALE AUX ETATS-UNIS

DoE : A21 à Argonne Labs (ANL)

□ A21 (ex Aurora) un système MPP hybride en 2021

- **1^{er} système Exacale US**, fourni par Intel et Cray, report du 1^{er} deal CORAL
- Axé convergence HPC / HPDA / AI
- Annonce 18 mars 2019 du DoE, budget 500M\$ (CAPEX)
 - Au moins 200 racks Shasta Cray
 - next gen Intel Xeon CPU 10 nm (3D Foveros) couplés à Intel X^e discrete GPU
 - mémoire persistente Optane DC
 - Interconnect Cray Slingshot Ethernet low latency, topologie Dragonfly, 200 Gbs
- Stack logicielle Intel OneAPI
 - Couche abstraction pour utilisation CPU, GPU, CSA, AI chips et FPGA

A21 FOM Applications

	Application	Summary
Simulation	HACC	Particle/N-Body, FFT
	LAMMPS	Classical MD
	QMCPACK	Many-Body Theory
	Nekbone	Unstructured Grids, Spectral Element
Data	LSST-SVM	Multi-class classification or regression analysis using support vector machines. Datasets consistent with those expected from future cosmological surveys.
	Tomography Reconstruction	Fourier Time method. Used 1D and 2D FFTs, interpolation, and approximation functions. Dataset includes images.
	FCMA (SGEMM & SSYRK)	Interactions among brain regions in functional magnetic resonance imaging Data is a stream of 3D human brain data (volumes of voxel) over time, 4D data
Learning	Candle Pilot 1 (P1B2, P1B3)	Convolution Neural Nets (CNN), Multilayer Perceptrons (MLP) Datasets include gene sequences, drug responses, drug descriptors.
	Candle Pilot 3 (P3)	Hierarchical Attention Networks, Multi-task Learning Datasets include ontology reports
	Imaging (Inference)	Convolution Neural Nets, GANs, MLP. Datasets include images and potentially experimental settings





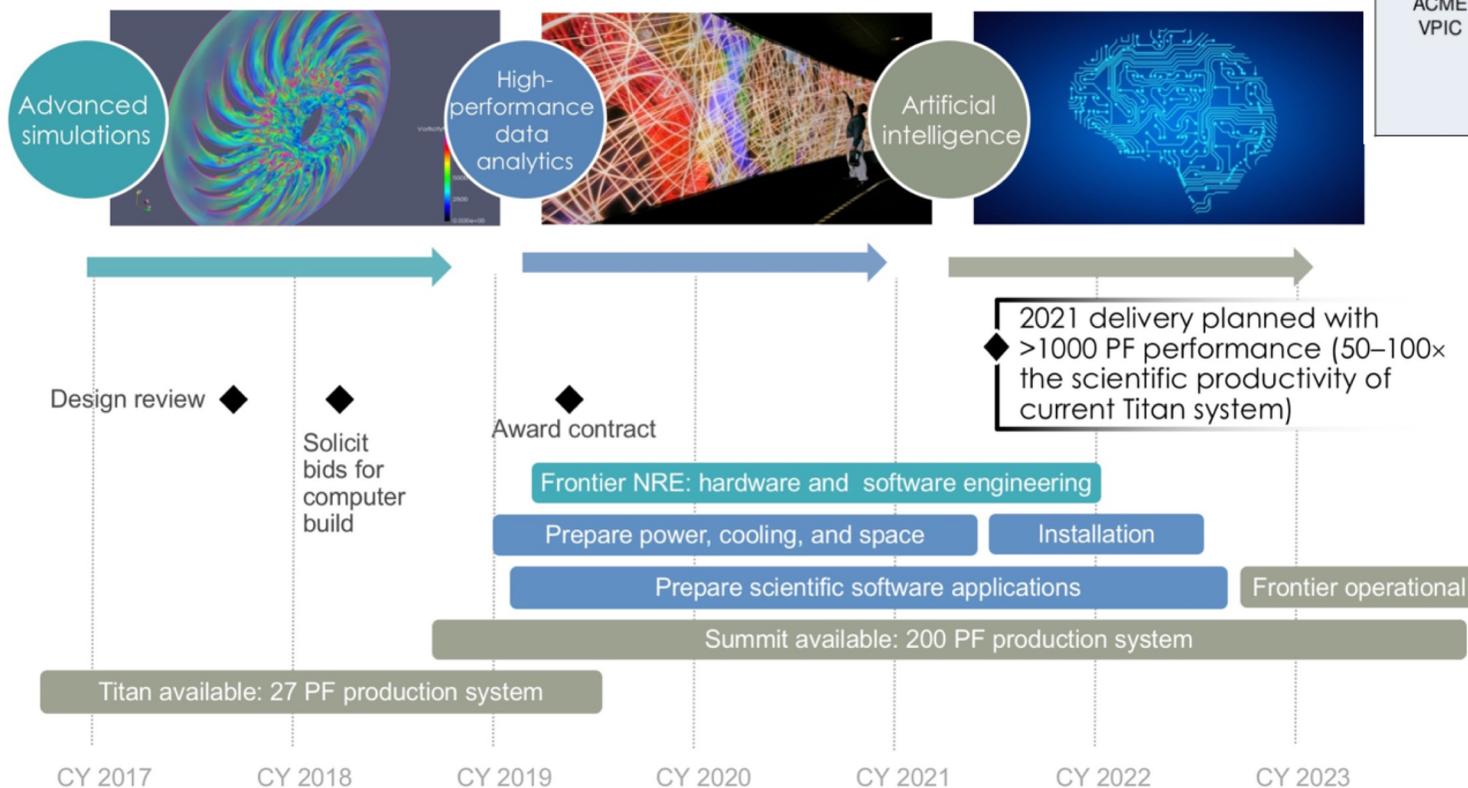
L'EXASCALE AUX ETATS-UNIS

DoE : Frontier à Oak Ridge National Laboratory (ORNL)

Appel d'offres CORAL2 du DoE (ORNL + LLNL)

- 1.8 Md\$ pour systèmes ORNL et LLNL + update système ANL
- Au moins 1300 PF (FP64) peak performance, 1 GB per MPI task et au moins 8 PB de mémoire totale, max 40MW, 20-30MW de préférence
- Au moins 50x / (Titan, Sequoia) sur apps publiques ->
- CRAY (AMD – CPU+GPU)

Scalable Science	Throughput	Data Science Deep Learning	Skeleton
QMCPACK HACC NEKbone ACME VPIC	Quicksilver Kripke LAMMPS AMG PENNANT Laghos	Integer sort Havoq Big Data Suite Deep Learning Suite	MPI suite Memory suite GEMM Pynamic CLOMP ML suite I/O suite RAJA suite Hash







L'EXASCALE EN CHINE

Contexte



Status of Chinese SC



Supercomputing Centers in China



CNGrid



NSCC-Guangzhou, 2013
Tianhe-2



NSCC-Wuxi, 2016
Shenwei-Taihu Light



NSCC-Changsha, 2012
Tianhe-1A



NSCC-Jinan, 2012
Shenwei-Bluelight



NSCC-Tianjin, 2010
Tianhe-1A



NSCC-Shenzhen, 2011
Dawning-6000

Courtesy : Yutong Lu



□ HPC, AI, Quantum = technos stratégiques pour la Chine (13^{ème} plan)

□ Exascale targets :

- Exaflops in peak performance with HPL efficiency >60%
- Node performance > 10 TF, >30 GF/W energy efficiency
- 10 PB memory and EB storage
- >400 Gbs interconnect b/w
- Large scale system management and resource, system monitoring and fault tolerance
- Support for large scale applications
 - Numerical nuclear reactor
 - Numerical aircraft (CFD, structure, MDO) and engines (4-stage unsteady LES simulation)
 - Astrophysics and earth system
 - Drug discovery and life sciences
 - Seismic and oil exploration
 - Material sciences
 - Complex engineering (ex: 3 Gorges full dam modeling)

□ 3 projets en compétition ;

1. NUDT : CPU scalaire + accélérateur (DSP)
2. NRCPC = manycore CPU
3. Dawning (Sugon) : processeur x86 (AMD) + accélérateurs (DCU)



L'EXASCALE EN CHINE

3 projets concurrents, systèmes convergés HPC/HPDA/AI

NUDT (Tianhe-3)

- Reconfigurable flexible heterogeneous arch.
- High-speed interconnect
- based on Chinese-designed Arm technology, likely some version of Phytium's Xiaomi
- ARM processor (>64 cores, > 2TF) + Matrix 3000 DSP accelerator (>96 cores, 10 TF, HBM2, support FP16)
- final version will be operational by 2020
- 200 times faster and 100 times more storage capacity than Tianhe-1
- Water cooling PUE<1.1

Sunway

- developed by the National Research Center of Parallel Computer Engineering and Technology (NRCPC)
- New manycore processor (evolution of the current 260-core ShenWei 26010)
- new interconnect
- expect to build the exascale computer in the second half of 2020 or the first half of 2021

Sugon

- home grown Hygon x86 (>1TF) + DCU accelerators (>15 TF) / node
- 400 Gbs 6D torus, 384 ports routers
- Less than 32768 nodes, with 32 TF/node
- China has a licensing agreement between Hygon and AMD (Zen 1 architecture for the moment)
- Immersive cooling technology (Imm058)



L'EXASCALE EN CHINE

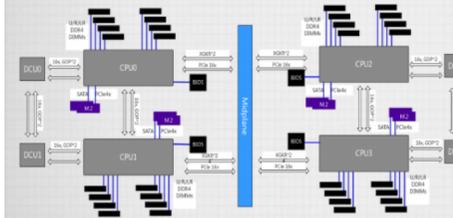
3 projets concurrents, systèmes convergés HPC/HPDA/AI

NRCPC exascale prototype system

- ❑ SW26010 CPU
 - ❑ Used in Sunway TaihuLight system
- ❑ 512 nodes
 - ❑ Each node has 2 CPUs
- ❑ Homegrown network

Sugon exascale prototype system

- ❑ Heterogenous architecture
 - ❑ Hygon CPU + DCU
- ❑ 6D torus network



National University of Defense Technology

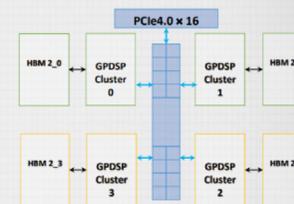
NUDT exascale prototype system

- ❑ 512 nodes
 - ❑ 3 MT-2000+ processors
 - ❑ 6Tflops peak performance
- ❑ Matrix-2000+
 - ❑ 128 cores
 - ❑ 2 GHz
 - ❑ 2 Tflops
 - ❑ ~130W, ~15Gflops/W
- ❑ 400Gbps homegrown network

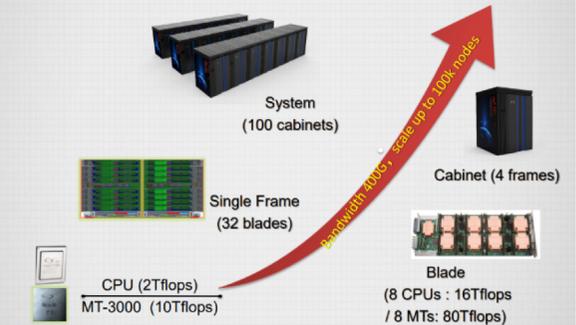


Matrix-3000

- ❑ GPDSP
- ❑ Cores >= 96, > 10 Tflops
- ❑ HBM2
- ❑ PCIe Gen4
- ❑ Support half precision



Tianhe-3



National University of Defense Technology



L'EXASCALE EN CHINE

Sur 1 slide les 3 projets en lice

	Sunway 2020	Sugon Exascale	NUDT 2020
Key User/Developer	Sunway/NRCPC	Sugon/AMD	NUDT
Planned Delivery Date/ Estimated	2020, 4Q (could slip 1-1.5 years)	2020, 4Q (could slip 1-1.5 years)	2020, 4Q (could slip 1-1.5 years)
Planned/Realized Performance (Pflops)	1000	1024	1000
Linpack Performance (PFlops)	600-700	627-732	700-800
Linpack/Peak Performance Ratio (%)	60-70	60-70 (est.)	70-80
High Performance Conjugate Gradient (Pflops/s)	6-7	9.4-10.1	14-16
GF/Watt	30	34.13	20-30
Linpack GF/Watt	20-23	20.9	23.3-32.0





EURO-HPC

Mutualiser pour aller vers l'Exascale



EuroHPC
Joint Undertaking

te



■ **Mission:** Establish an integrated world-class supercomputing and data infrastructure and support a highly competitive and innovative HPC and Big Data ecosystem

■ **Objectives**

1. **An integrated world-class supercomputing and data infrastructure**

- 2 pre-exascale + 2-3 petascale by 2020; 2 exascale by 2022/2023 (1 EU tech); post-exascale infrastructure by 2027
- federation of HPC infrastructures at European level
- hybrid HPC/Quantum infrastructure

2. **Research and innovation for a HPC and Big Data ecosystem**

- an integrated European HPC R&I agenda
- independent HPC technology supply
- excellence in HPC applications and use
- HPC Competence Centres, training/skills, outreach

Infrastructure & Operations

R&I: Tech, Apps & Skills

HPC Ecosystem

>1 Md€ alloués pour la 1^{ère} phase (Pré Exascale)

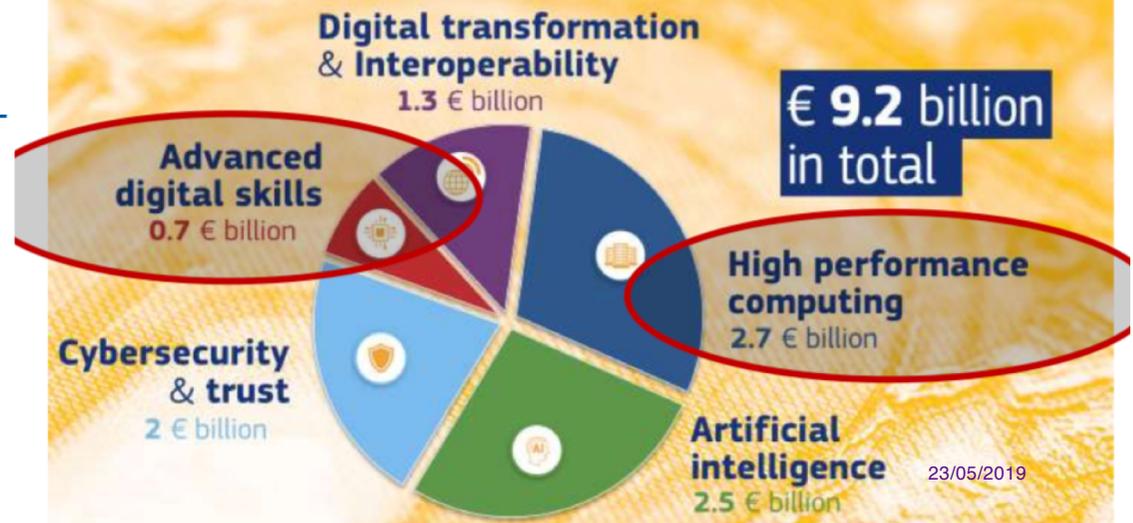
Plus de 3Md€ visés dans le FP9 pour la 2^{ème} phase (Exascale)



"Our goal is for Europe to become one of the top 3 world leaders in high-performance computing by 2020."

Jean-Claude Juncker, 27 October 2015

Investing in the future: Digital Europe Programme



Fin 2018 : 25 pays partenaires !



EXASCALE EN EUROPE



Le projet EPI : European Processor Initiative

One of the lighthouse R&I project of



Rolls-Royce
Motor Cars Limited



Barcelona
Supercomputing
Center
Centro Nacional de Supercomputación



ALMA MATER STUDIORUM
UNIVERSITÀ DI BOLOGNA



CHALMERS



UNIVERSITÀ DI PISA





EXASCALE EN EUROPE

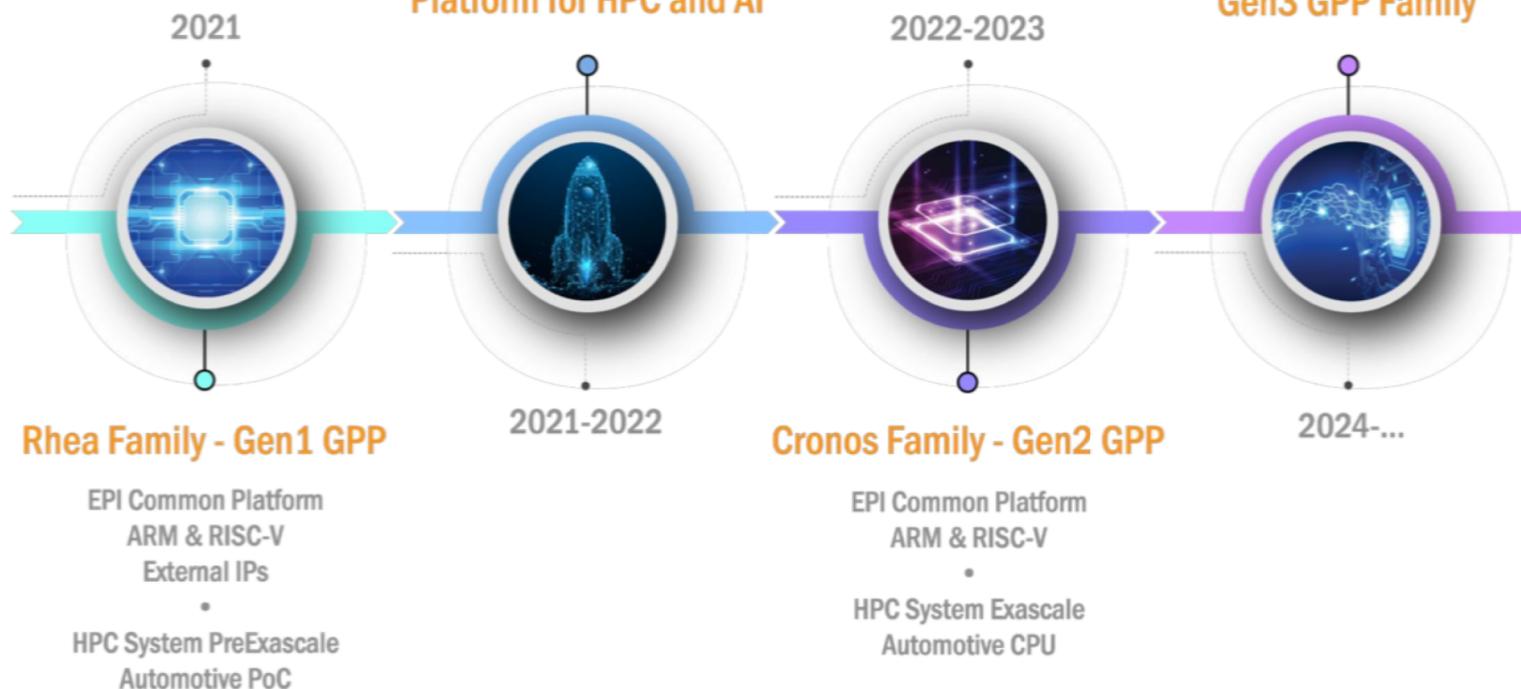


Le projet EPI : European Processor Initiative

Current roadmap



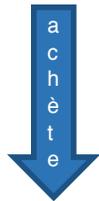
EPI IP's Launch Pad
&
Pan European Research
Platform for HPC and AI



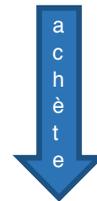


LA CONTRACTION DES ACTEURS

- Mouvements importants sur le marché du HPC sur les derniers 6 mois



Hewlett Packard
Enterprise



- D'autres mouvements à venir?



□ L'exascale est un projet cohérent à part entière :

- Pas du business-as-usual
- Nécessite de se définir des cibles applicatives et de travailler sur un couple {cibles applicatives ; architecture}
 - Sachant que les architectures doivent satisfaire à des contraintes fortes (comme la consommation énergétique par exemple)
 - L'adaptation (refonte) des codes est donc nécessaire – MAIS ne peut se faire indépendamment de l'archi HW
 - Comme l'archi HW ne peut se définir indépendamment des cibles applicatives

□ Nécessite la mobilisation de compétences complémentaires au service de l'objectif

- Ce n'est pas que du financement pour acheter et concevoir du matériel

□ Projet dans la durée

- Si le design d'une architecture exascale prend du temps, la conception d'une application pour l'exascale prend encore plus de temps !